

06-21-2004



102770822

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

22278 U.S. PTO
10/866393
061104

Applicant: Charles W.C. Lin
Assignee: Bridge Semiconductor Corporation
Title: SEMICONDUCTOR CHIP ASSEMBLY WITH PRESS-FIT
GROUND PLANE
Serial No.: Unknown Filed: Herewith
Examiner: Unknown Group Art Unit: Unknown
Atty. Docket No.: BDG032

6-11-04

COMMISSIONER FOR PATENTS
P.O. Box 1450
Alexandria, VA 22313-1450

ASSIGNMENT RECORDATION COVER SHEET

Dear Sir:

10866393

Please record the attached original Assignment.

1. Name of conveying party:

Charles W.C. Lin

2. Name and address of receiving party:

Bridge Semiconductor Corporation
3rd Floor, 157 Li-Te Road
Peitou District
Taipei, Taiwan 112

3. Nature of conveyance:

Assignment

The execution date of the Assignment is June 9, 2004.

06/18/2004 LMUELLER 00000131 502178 10866393

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-1-

PATENT
REEL: 015467 FRAME: 0662

4. Application number(s) or patent number(s)

This Assignment is being filed together with a new patent application. The execution date of the application is June 9, 2004.

5. Name and address of party to whom correspondence should be mailed:

David M. Sigmond
2440 Andrew Drive
Superior, Colorado 80027

(303) 554-8371

6. Total number of applications and patents involved: 1.

7. Total fee under 37 C.F.R. § 1.21(h): \$40.

8. Method of Payment:

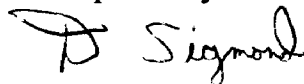
Charge the \$40 to Deposit Account No. 502178/BDG032 and charge any underpayment or credit any overpayment to this Account.

9. Statement and signature.

To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.

Total number of pages including cover sheet, attachments and document: 3.

Respectfully submitted,



David M. Sigmond
Attorney for Applicant
Reg. No. 34,013
(303) 554-8371
(303) 554-8667 (fax)

Date: 6/11/04



ASSIGNMENT

WHEREAS, I, CHARLES W.C. LIN of Singapore, have invented a certain new and useful invention entitled SEMICONDUCTOR CHIP ASSEMBLY WITH PRESS-FIT GROUND PLANE, for which an application for Letters Patent of the United States has been prepared for filing, said application being identified as Attorney Docket No. BDG032;

NOW THEREFORE, be it known that I, the said inventor, for and in consideration of certain good and valuable consideration, the sufficiency and receipt of which is hereby acknowledged, at the request of the assignee do sell, assign and transfer unto said assignee, BRIDGE SEMICONDUCTOR CORPORATION, a Taiwan Corporation having a place of business at 3rd Floor, 157 Li-Te Road, Peitou District, Taipei, Taiwan 112, its successors, legal representatives and assigns, the aforesaid application for the territory of the United States of America and all continuation, divisional, continuation-in-part and reissue applications, all patent applications in foreign countries, all applications pursuant to the Patent Cooperation Treaty, and all applications for extension filed or to be filed for the invention, and all Letters Patent, Invention Registrations, Utility Models, Extensions or Reissues, Reexaminations and other patent rights, obtained for the invention in the United States or any other country; I also assign any right, title or interest in and to the invention which has not already been transferred to the assignee; I warrant that I have made no assignment of the invention, application or patent therefor to a party other than BRIDGE SEMICONDUCTOR CORPORATION and I am under no obligation to make and shall not make any assignment of the invention, application, or patent therefor to any other party; and I further agree to cooperate with the assignee hereunder in obtaining, sustaining and enforcing of any and all such Letters Patent and patent rights and in confirming the assignee's exclusive ownership of the invention, without further consideration, but at the expense of said assignee.

The Commissioner of Patents is hereby authorized and requested to issue the Letters Patent solely in accordance with the terms of this Assignment to BRIDGE SEMICONDUCTOR CORPORATION, its successors, legal representatives and assigns, as the assignee of the entire right, title and interest therein.


IN WITNESS WHEREOF, the party hereto has executed this Assignment as of the date indicated hereunder.

Date: June 8, 2004

By: _____

CHARLES W.C. LIN

093士院認002

案 號	日期
Case No. 00098002	Date JUN - 9 2004
本文件之簽名或蓋章，在台灣士林地方法院公證處認 證。	
公證人 劉 富 貴	
Attested at the Notary Public Office of Taiwan Shihlin District Court, R.O.C., that the signature(s)/seal(s) in this document is/are authentic.	
Notary Public	 Liu, Fu-Kuei

-1-

PATENT

REEL: 015467 FRAME: 0664

ASSIGNMENT

WHEREAS, I, CHARLES W.C. LIN of Singapore, have invented a certain new and useful invention entitled SEMICONDUCTOR CHIP ASSEMBLY WITH PRESS-FIT GROUND PLANE, for which an application for Letters Patent of the United States has been prepared for filing, said application being identified as Attorney Docket No. BDG032;

NOW THEREFORE, be it known that I, the said inventor, for and in consideration of certain good and valuable consideration, the sufficiency and receipt of which is hereby acknowledged, at the request of the assignee do sell, assign and transfer unto said assignee, BRIDGE SEMICONDUCTOR CORPORATION, a Taiwan Corporation having a place of business at 3rd Floor, 157 Li-Te Road, Peitou District, Taipei, Taiwan 112, its successors, legal representatives and assigns, the aforesaid application for the territory of the United States of America and all continuation, divisional, continuation-in-part and reissue applications, all patent applications in foreign countries, all applications pursuant to the Patent Cooperation Treaty, and all applications for extension filed or to be filed for the invention, and all Letters Patent, Invention Registrations, Utility Models, Extensions or Reissues, Reexaminations and other patent rights, obtained for the invention in the United States or any other country; I also assign any right, title or interest in and to the invention which has not already been transferred to the assignee; I warrant that I have made no assignment of the invention, application or patent therefor to a party other than BRIDGE SEMICONDUCTOR CORPORATION and I am under no obligation to make and shall not make any assignment of the invention, application, or patent therefor to any other party; and I further agree to cooperate with the assignee hereunder in obtaining, sustaining and enforcing of any and all such Letters Patent and patent rights and in confirming the assignee's exclusive ownership of the invention, without further consideration, but at the expense of said assignee.

The Commissioner of Patents is hereby authorized and requested to issue the Letters Patent solely in accordance with the terms of this Assignment to BRIDGE SEMICONDUCTOR CORPORATION, its successors, legal representatives and assigns, as the assignee of the entire right, title and interest therein.

IN WITNESS WHEREOF, the party hereto has executed this Assignment as of the date indicated hereunder.

Date: June 9, 2004

By: _____

CHARLES W.C. LIN

093士院認002

案號	00098002	日期	JUN - 9 2004
Case No.		Date	
本文件之簽名或蓋章，在台灣士林地方法院公證處認 證。			
公證人 劉富貴			
Attested at the Notary Public Office of Taiwan Shihlin District Court, R.O.C., that the signature(s)/seal(s) in this document is/are authentic.			
Notary Public <u>Liu Fu-Kuei</u>			

-1-